



SLOVENSKI STANDARD

SIST EN 62132-1:2016

01-april-2016

Nadomešča:
SIST EN 62132-1:2006

Integrirana vezja - Meritve elektromagnetne odpornosti - 1. del: Splošni pogoji in definicije

Integrated circuits - Measurement of electromagnetic immunity - Part 1: General conditions and definitions

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ICS:

31.200	Integrirana vezja, mikroelektronika	Integrated circuits. Microelectronics
33.100.20	Imunost	Immunity

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EUROPEAN STANDARD

EN 62132-1

NORME EUROPÉENNE

EUROPÄISCHE NORM

February 2016

ICS 31.200

Supersedes EN 62132-1:2006

English Version

Integrated circuits - Measurement of electromagnetic immunity - Part 1: General conditions and definitions (IEC 62132-1:2015)

Circuits intégrés - Mesure de l'immunité électromagnétique
- Partie 1: Conditions générales et définitions
(IEC 62132-1:2015)

Integrierte Schaltungen - Messung der elektromagnetischen
Störfestigkeit - Teil 1: Allgemeine Bedingungen und Begriffe
(IEC 62132-1:2015)

This European Standard was approved by CENELEC on 2015-12-03. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 62132-1:2016**European foreword**

The text of document 47A/974/FDIS, future edition 2 of IEC 62132-1, prepared by SC 47A "Integrated circuits" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62132-1:2016.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2016-09-03
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2018-12-03

This document supersedes EN 62132-1:2006.

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Endorsement notice

The text of the International Standard IEC 62132-1:2015 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

		<u>SIST EN 62132-1:2016</u>
IEC 61400-4-3	NOTE	Harmonized as EN 61400-4-3. https://standards.iteh.ai/catalog/standards/sist/af8449b4-7772-4eaa-9523-a0107148d448
IEC 61400-4-6	NOTE	Harmonized as EN 61400-4-6.
IEC 61967-1:2002	NOTE	Harmonized as EN 61967-1:2002.
CISPR 20	NOTE	Harmonized as EN 55020.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62132-2	-	Integrated circuits - Measurement of electromagnetic immunity -- Part 2: Measurement of radiated immunity - TEM cell and wideband TEM cell method	EN 62132-2	-
IEC 62132-3	-	Integrated circuits - Measurement of electromagnetic immunity, 150 kHz to 1 GHz -- Part 3: Bulk current injection (BCI) method	EN 62132-3	-
IEC 62132-4	-	Integrated circuits - Measurement of electromagnetic immunity, 150 kHz to 1 GHz -- Part 4: Direct RF power injection method	EN 62132-4	-
IEC 62132-5	-	Integrated circuits - Measurement of electromagnetic immunity, 150 kHz to 1 GHz -- Part 5: Workbench Faraday cage method	EN 62132-5	-
IEC 62132-8	-	Integrated circuits - Measurement of electromagnetic immunity -- Part 8: Measurement of radiated immunity - IC stripline method	EN 62132-8	-
IEC/TS 62132-9	-	Integrated circuits - Measurement of electromagnetic immunity - Part 9: Measurement of radiated immunity - Surface scan method	-	-

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IEC 62132-1

Edition 2.0 2015-10

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Integrated circuits – Measurement of electromagnetic immunity –
Part 1: General conditions and definitions**

**Circuits intégrés – Mesure de l'immunité électromagnétique –
Partie 1: Conditions générales et définitions**

INTERNATIONAL
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**INTEGRATED CIRCUITS –
MEASUREMENT OF ELECTROMAGNETIC IMMUNITY –****Part 1: General conditions and definitions**

FOREWORD

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International Standard IEC 62132-1 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2006 and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) frequency range of 150 kHz to 1 GHz has been deleted from the title;
- b) frequency step above 1 GHz has been added in Table 2 in 7.4.1;
- c) IC performance classes in 8.3 have been modified;
- d) Table A.1 was divided into two tables, and references to IEC 62132-8 and IEC 62132-9 have been added in the new Table A.2 in Annex A.

The text of this standard is based on the following documents:

FDIS	Report on voting
47A/974/FDIS	47A/977/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62132 series, published under the general title *Integrated circuits – Measurement of electromagnetic immunity*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

The IEC 62132 series is published in several parts, under the general title *Integrated circuits – Measurement of electromagnetic immunity*:

- Part 1: General conditions and definitions
- Part 2: Measurement of radiated immunity – TEM cell and wideband TEM cell method
- Part 3: Bulk current injection (BCI) method
- Part 4: Direct RF power injection method
- Part 5: Workbench Faraday cage method
- Part 8: Measurement of radiated immunity – IC stripline method
- Part 9: Measurement of radiated immunity – Surface scan method

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